External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.03428	100.0	0.68
	Doped silicon	Silicon (Si)	7440-21-3	0.24198	100.0	4.8
	Doped silicon	Silicon (Si)	7440-21-3	0.01008	100.0	0.2
			Subtotal	0.28634	300	5.68
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02072	0.03	0.41106
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.02072	0.03	0.41106
	Copper alloy	Iron (Fe)	7439-89-6	0.06908	0.1	1.3702
	Copper alloy	Copper (Cu)	7440-50-8	68.96499	99.84	1,368.00768
			Subtotal	69.07551	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.1599	4.0	23.008
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.34961	15.0	86.28
	Filler	Silica fused	60676-86-0	21.45807	74.0	425.648
	Flame retardant	Metal hydroxide		2.02982	7.0	40.264
			Subtotal	28.9974	100	575.2
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.39139	100.0	27.6
			Subtotal	1.39139	100	27.6
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00637	100.0	0.12644
	Pure metal	Aluminium (Al)	7429-90-5	0.08167	100.0	1.62
			Subtotal	0.08804	200	1.74644
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00323	2.0	0.064
	Lead alloy	Silver (Ag)	7440-22-4	0.00403	2.5	0.08
	Lead alloy	Lead (Pb)	7439-92-1	0.15406	95.5	3.056
	Dicyandiamide	Dicyandiamide (generic)	461-58-5	0	0.5	0
	Phenolic resin	Phenolic resin		0	2.5	0
	Epoxy resin	Epoxy resin system		0	20.0	0
	Lead alloy	Silver (Ag)	7440-22-4	0	77.0	0
			Subtotal	0.16132	200	3.2
			Total	100	100	NaN

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